

Conference Location

The conference will be held at Radisson Resort & Spa Scottsdale, 7171 North Scottsdale Road, Scottsdale, Arizona 85253-3696, phone 480-991-3800. The hotel is holding a block of rooms for participants at a special rate of \$145.00 single or double occupancy plus tax. There is a one-time resort service charge of \$5.00 per person which covers check-in/check-out and \$1.00 per room per night for a room attendant gratuity. These charges will be placed on the individual room account. Reservations may be made by calling the hotel directly or the Worldwide Reservation Center at 1-800-333-3333. Reservations must be made by September 21, 2000 to receive these rates. After this time reservations will be accepted on a space available basis only. Please be sure to mention you are attending the Electrical Performance of Electronic Packaging Conference. All reservations must be guaranteed with one room night's deposit in the form of a check or credit card. Check-in time is 4:00 p.m. Check-out time is 12:00 noon.

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The Institute of Electrical
and Electronic Engineers, Inc.

Announcement and Call for Papers

9th Topical Meeting on Electrical Performance of Electronic Packaging EPEP 2000

Sponsors

The IEEE Microwave
Theory and Techniques Society

and

The IEEE Components,
Packaging and Manufacturing
Technology Society

October 23 – 25, 2000
Radisson Resort & Spa Scottsdale
Scottsdale, Arizona



<http://intermix.engr.arizona.edu/~epd/#EPEP>

First Call for Papers

Co-Chairs:

Ravi Kaw, Agilent Technologies

John L. Prince, The University of Arizona

The general subject of the meeting is the electrical modeling, design, analysis, and characterization of electronic interconnections and packaging structures. A forum will be provided for the discussion of the following topics as they relate to chip-to-chip and on-chip interconnections in electronic systems:

Package analysis, including numerical methods and algorithms; Electro-magnetic analysis tools; Advances in transmission-line techniques; Power distribution and package resonance; Switching noise in multi-layered structures.

RF/microwave packaging structures and their electrical performance;

Multilayer LTCC packaging for microwave applications;

MMIC modules and high density packaging;

Experimental characterization techniques and testing procedures;

EMC/EMI sources & effects; Prediction and measurement of radiation from

On-chip sources, inter-connect structures and packaged systems;

Long distance propagation in large switching complexes.

New and innovative interconnect packaging structures and their electrical performance;

Electrical design implications for low cost, high volume packaging.

Packaging concerns for wireless communication: design and modeling;

Packaging solutions for one chip radios: design and modeling;

Performance of low cost packaging solutions for communications systems;

Performance of packaging for automotive radar systems;

Optoelectronic packaging; structure and system applications.

Current and future issues related to on-chip interconnections;

Router friendly models and modeling tools: accuracy & efficiency;

Modeling and Design of high speed digital IO circuits: signal propagation and reception;

On-chip power delivery and regulation;

Advances in modeling core switching noise, and design of novel solutions;

On-chip measurement techniques.

This is the ninth meeting in this topical series. The last meeting was very well attended and was held in San Diego, California, during October 25-27, 1999.

Additional information may be obtained from the conference co-chairs:

Ravi Kaw

Email: ravi_kaw@agilent.com

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FAX: 650-852-8676 or

John L. Prince

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Copies of the 1999 meeting's digest can be obtained from IEEE by requesting the publication catalog number 99TH8412 at phone: 908-981-0060 or FAX: 908-981-0027.

Conference Web Page

Updated information about the conference can also be found on the web page at:

<http://intermix.engr.arizona.edu/~epd/#EPEP>

Paper Submission

Authors are invited to submit papers describing new technical contributions in the areas broadly covered

above. The original and three copies of a summary, not to exceed FOUR PAGES, in single-column format, including illustrations, are required for paper selection. The listed topic categories will be used to determine the appropriate reviewers for the submitted papers. In your cover letter, prioritize three key words from the list that best represent your paper. All papers must be written in English. The title of the paper and the names and affiliations of all authors, including complete mailing addresses, telephone, FAX numbers and emails must appear on the first page of the summary, as well as a 35 word abstract. FAX and email are absolutely necessary since all paper acceptance notifications and further communications will be done via one of these media. If the paper is accepted, the summary will be reproduced, as is, in the meeting's digest. An IEEE transfer of copyright, found in most IEEE journals, must accompany each submission. Submissions should be sent, not later than July 10, 2000, to the address given on the next page.

Best Student Paper Award

Two special awards will be presented to the best two papers submitted and presented by a student. To be considered for the award, the student must be the lead author and must present the paper at the meeting. A statement must be attached by the student's faculty advisor certifying that the lead author is a bona fide student at the cited institution.

Short Courses/Lectures

Short courses and one-hour lectures will be offered on October 22, 2000, the Sunday before the start of the conference. Proposals or suggestions for these courses and lectures should be submitted to the co-chairs by July 10, 2000.

Product and Advertisement Displays

Parties interested in displaying products and software packages at this meeting should contact the address given on the next page. Individual company sponsorship of the breaks is greatly appreciated, and facilities are provided for displaying advertising materials.